



中山市晶明光电科技有限公司
ZHONGSHAN SILSMART OPTOELECTRONICS CO., LTD.

样品规格书

SPECIFICATION

产品名称：0.47 “四位米字数码管 Product Name: LED Display	发光颜色:红色 Emitted Color: Red	封胶：封胶 Filler: Resin
产品型号： Product No: JMF-4473BS4-059-P4.0	极性：共阳 Polarity: Common Anode	面色：黑面白胶
产品编码： Product Code:	样品单号： Sample NO:	
注：所有材料均符合 ROHS 要求 All materials are RoHS compliant!		

日期:2019/6/25 Date:	承办人:叶开波 Issuer:
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客户确认 APPROVED BY

客户： Customer:	签名： Signature:
机型： Model No:	日期： 2016/6/14
料号： Part No:	Date:

结论 Result:

确认后请回传 PLEASE RETURN BY A COPY

设计 (DESIGN): _____ 检查 (CHECKED): _____ 批准 (APPROVED): _____
产品说明书



1. 极限参数 (Absolute Maximum Ratings)

(1) 红色(Red)

参数 (Parameter)	符号 (Symbol)	极限值 (Maximum)	单位 (Unit)
功耗 (Power Dissipation)	Pd	50	mW
脉冲电流 (Peak Forward Current)	Ifp	90	mA
直流电流 (Continuous Forward Current)	Ifm	20	mA
反向电压 (Reverse Voltage)	VR	5	V
工作温度 (Operating Temperature Range)	Topr	-20 → +85	°C
储藏温度 (Storage Temperature Range)	Tstg	-20 → +85	°C
静电电压 (Static Voltage)	Var		V

*焊接温度 (Lead Soldering Temperature): 260°C for 3 seconds

*当工作温度高于 25°C 时, Ifm、Ifp、Pd 必须降低; 电流降低率是-0.36mA/°C (直流驱动), 或-0.86mA/°C (脉冲驱动) 功耗降低率是-0.75mW/°C。

The Ifm Ifp & Pd must be decreased once the temperature is over 25 °C; the Current decrease rate is: -0.36mA/°C (Direct Current); -0.86mA/°C (Pulse drive) the power dissipation is -0.75mW/°C

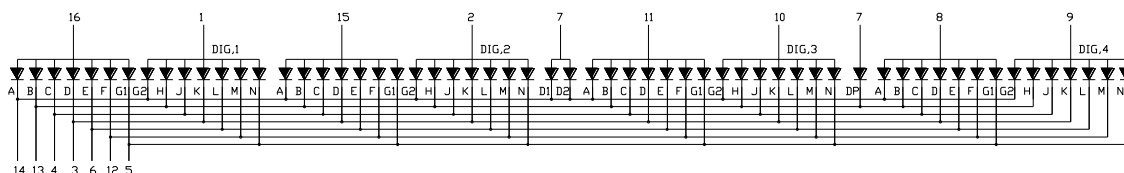
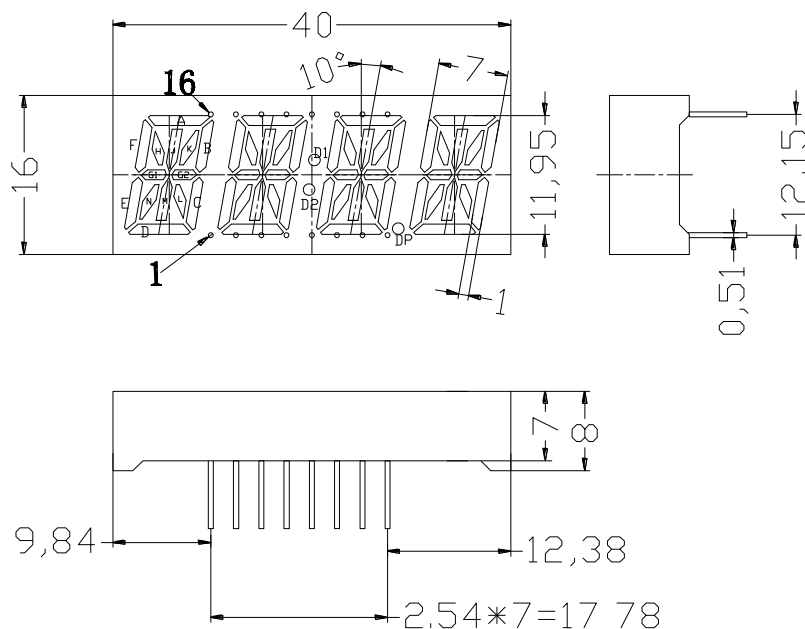
2. 光电特性 (Optical-Electrical Characteristic)

(1) 红色(Red)

参数 (Parameter)	测试条件 (Test)	符号 (Symbol)	Min	Type	Max	单位 (Unit)
发光强度 (Luminous Intensity)	If=20mA	Iv	80		94	Mcd
正向电压 (Forward Voltage)	If=20mA	VF	1.7		2.5	V
反向电流 (REVERSE Current)	VR = 5V	IR	-	-	50	uA
主波长 (Wavelength)	If=20mA	λD	620		625	nm
查看角度 (View Angle)	If=20mA	2θ1/2	-	60	-	Deg.

3.结构尺寸、原理图 (Mechanical Dimension and Circuit Diagram) :

(未注尺寸公差 Unspecified Tolerances is: $X \pm 0.2$)



4.保存和焊接条件 (Storage & Soldering Conditions) :

- Store with care. Storing the units in bad condition will decrease the adhesive power between the reflector and film. 注意保存, 保存条件不好时, 会降低膜片与反射壳(导光板)的粘附力。 Recommend storage condition : temperature ($25^{\circ}\text{C} \pm 10^{\circ}\text{C}$) 推荐保存条件为: 温度 $25^{\circ}\text{C} \pm 10^{\circ}\text{C}$ and humidity ($65^{\circ}\text{C CRH} \pm 20^{\circ}\text{C CRH}$) 湿度 $65^{\circ}\text{C CRH} \pm 20^{\circ}\text{C CRH}$
- The Soldering Temperature is $260 \pm 5^{\circ}\text{C}$ and Soldering time should be less than 3 seconds, and soldering iron power should be less than 30W. 焊接温度 $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$, 焊接时间小于 3 秒, 烙铁功率小于 30W。
- The soldering point should be at least 1.6mm away from the body. 焊接点应离产品实体大于 1.6mm。



5. 光电特性曲线 (Typical Electro optical Characteristics Curve):

